sink device **400**. In other examples, the heat sink **504** and the Peltier device **404** may be supported at other sides of the heat sink device **400**.

The heat sink device **400** also includes one or more fans **506** (e.g., a fan). The fan **506** may be any number of types of fans. In one example, the fan **506** is an axial fan. Other types of fans may be provided. The fan **506** may be any number of sizes. The size of the fan **506** may be set based on a maximum power of the Peltier device **404** or a maximum amount of heat to be dissipated by the heat sink device **400**. In the example shown in FIG. **5**, the fan **506** is supported at or adjacent to the top **408** and/or one or more of the sides **410** of the housing **402**. For example, the fan **506** is physically connected to the housing **402**, adjacent to the top **408** of the housing **402** with one or more connectors **508** (e.g., screws, nut/bolt combinations, tapped recesses). In other examples, the fan **506** is physically connected to other portions of the housing **402** (e.g., the bottom **500** of the housing **402**). The fan **506** is aligned with a portion of the heat sink **504** (e.g., fins of the heat sink **504**) and/or with one or more outlet vents **510** through the housing **402** of the heat sink device **400**. Cooling air is pulled into the housing **402** through inlet vents **512** by the fan **506**, and the cooling air is pushed through the heat sink **504** (e.g., the fins of the heat sink **504**) and out of the outlet vents **510** through the housing **402**. In one example, a speed of the fan **506** is controlled by a processor of the heat sink device **400** (not shown) or a processor of a computing device supported by and in communication with the heat sink device **400**. In another example, the speed of the fan **506** is set to one speed and remains at the speed while powered on.

FIG. **6** depicts detail B of the example of the heat sink device **400** of FIG. **5**. The Peltier device **404** includes a top **600**, a bottom **602**, and at least one side **604** extending between the top **600** and the bottom **602**. The Peltier device **404** may be any number of shapes including, for example, square or rectangular. The top **600** of the Peltier device **404** may be exposed. Alternatively, the top **600** of the Peltier device **404** may be covered by one or more layers of material. For example, one or more layers of a no residue thermal interface material may be applied to the top **600** of the Peltier device **404**.

The Peltier device **404** extends above the top **408** of the heat sink device **400**. The Peltier device **404** is maintained in the raised position relative to the top **408** of the heat sink device **400** with the heat sink **504**. In the example shown in FIGS. **4-6**, the heat sink **504** is a spring-loaded heat sink. The heat sink **504** may be physically connected to a part of the heat sink device **400** with one or more connectors **606** (e.g., four screws or bolts) about which springs **608** are wrapped. When the connectors **606** are tightened into the part of the heat sink device **400** (e.g., one or more tapped recesses in the heat sink device **400**) and thus onto the springs **608**, the springs **608** press against extensions of the heat sink **504** (e.g., bosses or flanges **610**). The springs **608** thus press the heat sink **504** against the part of the heat sink device **400**. The spring loading of the heat sink **504** may take other forms.

The spring loading of the heat sink **504** presses a surface **611** (e.g., a bottom) of the heat sink **504** against the bottom **602** of the Peltier device **404**, pushing the Peltier device **404** through the opening **502** through the top **408** of the heat sink device **400**. The contact between the heat sink **504** and the Peltier device **404** keeps the Peltier device **404** in position while also allowing the Peltier device **404** to move relative to the top **408** of the heat sink device **400** when a force is applied to the Peltier device **404** (e.g., during docking of a

computing device with the heat sink device **400**). The movement of the Peltier device **404** relative to the top **408** of the heat sink device **400** reduces forces on the computing device during docking.

As shown in the example of FIG. **6**, the heat sink device **400** also includes a transceiver module **612**. The transceiver module **612** may be any number of different types of transceivers including, for example, an optical transceiver, an RF transceiver, or another type of transceiver. At least part of the transceiver module **612** extends through an opening **614** through, for example, the top **408** of the heat sink device **400**. The transceiver module **612** may be located in other positions within the housing **402** of the heat sink device **400**. The transceiver module **612** may be supported by the housing **402** of the heat sink device **400** in any number of ways including, for example, with an adhesive.

The part of the transceiver module **612** that extends through the opening **614** through the top **408** of the heat sink device **400** is, for example, a protrusion **616** (e.g., a pin) used to locate the computing device on the heat sink device **400**. The protrusion **616** may provide a communications function (e.g., an electrical connection) in addition to the locating function. Alternatively, the protrusion **616** may only provide the locating function. For example, the transceiver module **612** may be an optical transceiver module, and the protrusion **616** may be a clear plastic part through which optical signals may be transmitted.

Signals received from the computing device via the transceiver module **612** may be transmitted to a processor of the heat sink device **400** (not shown) for processing, to the fan **506** for control, to the Peltier device **404** for control, or may be transmitted to a device external of the heat sink device **400**. For example, signals received from the computing device via the transceiver module may be transmitted to an external display for processing and display of data. The signals received from the computing device via the transceiver module **612** may be transmitted via wire or wirelessly.

FIG. **7** depicts a bottom view of the example of the heat sink device **400** of FIG. **4** with the bottom **500** removed. FIG. **7** shows the fan **506** and the heat sink **504**. The heat sink **504** includes a plurality of fins **700** through which air is pulled or pushed by the fan **506**. The plurality of fins **700** may be any number of sizes and shapes. For example, the plurality of fins **700** include rectangular fins and/or pin fins. The plurality of fins **700** may be uniform in shape and/or size or may vary in shape and/or size. The fan **506** may be powered from a power source inside the heat sink device **400** or outside the heat sink device **400**. For example, the fan **506** may be powered by batteries or a power supply unit included within the heat sink device **400**, or via a cable connected to a power source outside the heat sink device **400**.

The heat sink device **400** also includes one or more magnets **702** positioned at or adjacent to the top **408**, the bottom **500**, and/or the at least one third side **410** of the heat sink device **400**. In the example shown in FIG. **7**, the heat sink device **400** includes two magnets **702** (one magnet visible in FIG. **7**), positioned adjacent to the top **408** of the heat sink device **400**. The magnets **702** may be physically attached to an internal surface **704** of the heat sink device **400** in any number of ways including, for example, with an adhesive. The respective positions of the magnets **702** may correspond to relative positions of magnets within computing devices to be supported and cooled by the heat sink device **400**. For example, a distance between the magnets **702** may be the same as a distance between magnets of the mobile phone **202**, for example.